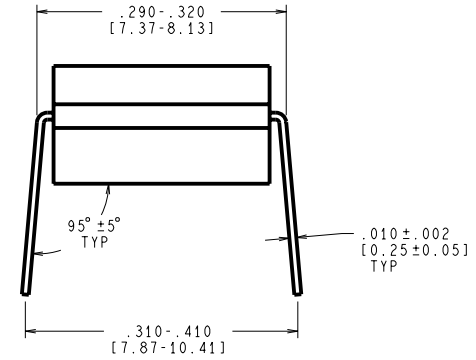
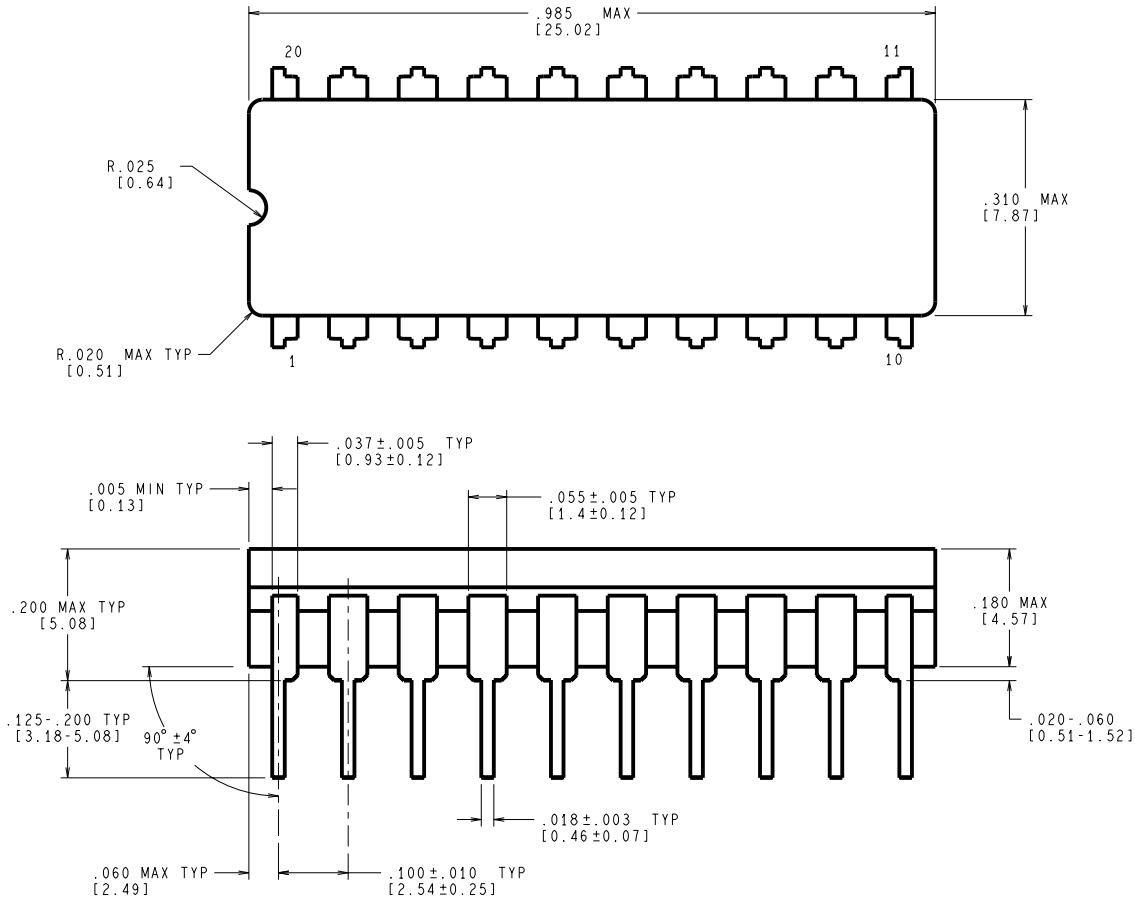


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
N	REVISE AND REDRAW PER CURRENT STANDARD; UPDATE TITLE & MIL/AERO STAMP.	11696	03/27/1997	MS/



CONTROLLING DIMENSION IS INCH
 VALUES IN [] ARE MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

1. LEAD FINISH TO BE ONE OF THE FOLLOWING:
 - a. 200 MICROINCHES/ 5.08 MICROMETERS MINIMUM SOLDER MEASURED AT THE CREST OF THE MAJOR FLATS.
 - b. 200 TO 800 MICROINCHES/ 5.08 TO 20.32 MICROMETERS TIN PLATE OVER 50 TO 300 MICROINCHES/ 1.27 TO 7.62 MICROMETERS NICKEL UNDERPLATE OR BASIS METAL.
 - c. 50 TO 100 MICROINCHES/ 1.27 TO 2.54 MICROMETERS GOLD OVER 50 TO 350 MICROINCHES/ 1.27 TO 8.89 MICROMETERS NICKEL UNDERPLATE.
2. NO JEDEC REGISTRATION AS OF 03/27/1997.

MIL-PRF-38535
 CONFIGURATION CONTROL

APPROVALS		DATE	 2900 Semiconductor dr., Santa Clara, CA 95052-8090			
DRAWN MARTA SUCHY		03/27/1997				
DFTG. CHK.						
ENGR. CHK.						
 INCH [MM]			SCALE	SIZE	DRAWING NUMBER	REV
			N/A	C	(SC)MKT-J20A	N
DO NOT SCALE DRAWING			SHEET 1 of 1			